

L Number	Hits	Search Text	DB	Time stamp
3	334	(increas\$3 rais\$3) with height with solder	USPAT	2004/08/20 11:41
4	26	(increas\$3 rais\$3) with height with solder with material	USPAT	2004/08/20 14:06
5	5	((semi\$1conductor adj laser) near3 (plural\$3 multiple several)) and (((integrated mono\$1lithic\$4) with (photodetect\$3 detect\$3) with (laser ((light radiation) adj (source emit\$4)))) same (tracking near3 (signal error detection)) same (focus\$4 near3 (signal error detection)))	USPAT	2004/08/20 14:12
9	957	369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error signal)) same (amplifier))	USPAT	2004/08/20 17:11
10	186	369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error signal)) same (amplifier)) and ((plural\$3 multiple second) near3 (laser ((light radiation) adj (source emit\$4))))	USPAT	2004/08/20 17:13
11	8	369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error signal)) same (amplifier) same ((arithmetic arithmetic) same circuit)) and ((plural\$3 multiple second) near3 (laser ((light radiation) adj (source emit\$4))))	USPAT	2004/08/20 17:14
12	5	369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error signal)) same (amplifier) same ((arithmetic arithmetic) adj circuit)) and ((plural\$3 multiple second) near3 (laser ((light radiation) adj (source emit\$4))))	USPAT	2004/08/20 17:17
13	18	369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error signal)) same (amplifier) same ((arithmetic arithmetic) adj circuit))	USPAT	2004/08/20 17:42
16	20	369/\$7.ccls. and ((heat adj sink\$3) with (semiconductor adj laser) with substrate)	USPAT	2004/08/20 18:01
21	0	369/\$7.ccls. and (stress\$3 with (relax\$3 reduc\$4 lower\$3 compensat\$3) with (semiconductor adj laser) with substrate)	USPAT	2004/08/20 18:02
22	0	369/\$7.ccls. and (stress\$3 with (semiconductor adj laser) with substrate)	USPAT	2004/08/20 18:04
23	7	369/\$7.ccls. and (stress\$3 with (laser ((light radiation) adj (source emit\$4))) with substrate)	USPAT	2004/08/20 18:04
-	3	tokuda-masahide.in.	US-PGPUB	2004/08/20 11:41
-	31	substrate and mount\$3 and solder\$3 and ((first second plural\$3 multiple) with (electrode contact)) and height	EPO; JPO; IBM_TDB	2004/07/28 10:30
-	9	substrate and mount\$3 and solder\$3 and ((first second plural\$3 multiple) with (electrode contact)) and height and ((optical semi\$1conductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source))	EPO; JPO; IBM_TDB	2004/07/28 11:08
-	1	(solder\$3 with height) and (solder\$3 with volume) and 369/\$7.ccls.	USPAT; US-PGPUB	2004/07/28 11:25
-	1	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and 369/\$7.ccls.	USPAT; US-PGPUB	2004/07/28 11:26
-	720	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and ((optical semi\$1conductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source))	USPAT; US-PGPUB	2004/07/28 11:26

-	147	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and (((optical semiconductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source)) same substrate same mount\$3 same solder\$3)	USPAT; US-PGPUB	2004/07/28 11:27
-	137	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and (((optical semiconductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source)) same substrate same mount\$3 same solder\$3) and (contact electrode)	USPAT; US-PGPUB	2004/07/28 11:28
-	96	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and (((optical semiconductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source)) with mount\$3) same substrate same solder\$3) and (contact electrode)	USPAT; US-PGPUB	2004/07/28 11:29
-	75	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and (((optical semiconductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source)) with mount\$3 with substrate) same solder\$3) and (contact electrode)	USPAT; US-PGPUB	2004/07/28 11:29
-	51	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and (((optical semiconductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source)) with mount\$3 with substrate with solder\$3) and (contact electrode)	USPAT; US-PGPUB	2004/07/28 11:29
-	23	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and (((optical semiconductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source)) with mount\$3 with substrate with solder\$3) same (contact electrode))	USPAT; US-PGPUB	2004/08/02 14:17
-	1	20030147333.pn.	USPAT; US-PGPUB	2004/08/02 14:17
-	930	228/180.22.ccls.	USPAT; US-PGPUB	2004/08/05 13:50
-	687	228/180.1.ccls.	USPAT; US-PGPUB	2004/08/05 13:50
-	775	228/180.21.ccls.	USPAT; US-PGPUB	2004/08/05 13:50
-	287	228/245.ccls.	USPAT; US-PGPUB	2004/08/05 13:50
-	380	228/246.ccls.	USPAT; US-PGPUB	2004/08/05 13:50
-	758	228/254.ccls.	USPAT; US-PGPUB	2004/08/05 13:50
-	1412	257/737.ccls.	USPAT; US-PGPUB	2004/08/05 13:51
-	1318	257/738.ccls.	USPAT; US-PGPUB	2004/08/05 13:51
-	5249	228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls. 228/246.ccls. 228/254.ccls. 257/737.ccls. 257/738.ccls.	USPAT; US-PGPUB	2004/08/05 14:06
-	4520	228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls. 228/246.ccls. 228/254.ccls. 257/737.ccls. 257/738.ccls.	USPAT	2004/08/05 13:51
-	3742	(228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls. 228/246.ccls. 228/254.ccls. 257/737.ccls. 257/738.ccls.) and (step\$3 notch\$2 groov\$2)	USPAT; US-PGPUB	2004/08/05 14:07
-	383	(228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls. 228/246.ccls. 228/254.ccls. 257/737.ccls. 257/738.ccls.) and (step\$3 notch\$2 groov\$2) and optical	USPAT; US-PGPUB	2004/08/05 14:07

-	110	(228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls. 228/246.ccls. 228/254.ccls. 257/737.ccls. 257/738.ccls.) and ((step\$3 notch\$2 groov\$2) same optical)	USPAT; US-PGPUB	2004/08/05 14:09
-	343	(228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls. 228/246.ccls. 228/254.ccls. 257/737.ccls. 257/738.ccls.) and ((step\$3 notch\$2 groov\$2) same (optical laser ((light radiation) adj (source emit\$4))))	USPAT; US-PGPUB	2004/08/05 14:10
-	206	(228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls. 228/246.ccls. 228/254.ccls. 257/737.ccls. 257/738.ccls.) and ((step\$3 notch\$2 groov\$2) with (optical laser ((light radiation) adj (source emit\$4))))	USPAT; US-PGPUB	2004/08/05 15:02
-	17	5283446.URPN.	USPAT	2004/08/05 14:15
-	189	((step\$3 notch\$2 groov\$2) with (optical laser ((light radiation) adj (source emit\$4)))) same substrate same solder\$3 same (contact electrode)	USPAT; US-PGPUB	2004/08/05 15:03
-	189	((stepped step notch notched groove grooved) with (optical laser ((light radiation) adj (source emit\$4)))) same substrate same solder\$3 same (contact electrode)	USPAT; US-PGPUB	2004/08/05 15:04
-	145	((stepped step notch notched groove grooved) with (optical laser ((light radiation) adj (source emit\$4)))) same substrate same solder\$3 same (contact electrode same (align\$4 positioning))	USPAT; US-PGPUB	2004/08/05 15:05
-	143	((stepped step notch notched groove grooved) with (optical laser ((light radiation) adj (source emit\$4)))) same substrate same solder\$3 same (contact electrode same ((align\$4 positioning) with (optical laser ((light radiation) adj (source emit\$4))))	USPAT; US-PGPUB	2004/08/05 15:05
-	97	((stepped step notch notched groove grooved) with (optical laser ((light radiation) adj (source emit\$4)))) same substrate same solder\$3 same (contact electrode same ((align\$4 positioning) with (optical laser ((light radiation) adj (source emit\$4))))	USPAT	2004/08/05 16:46
-	40	YAMADA-TAKAO.in.	USPAT	2004/08/05 15:32
-	610	YAMADA-TAKAO.in.	USPAT; EPO; JPO	2004/08/05 15:33
-	51	YAMADA-TAKAO.in. and laser	USPAT; EPO; JPO	2004/08/05 15:33
-	45	YAMADA-TAKAO.in. and laser and nichia.as.	USPAT; EPO; JPO	2004/08/05 15:40
-	347	(gallium adj nitride) with laser	USPAT	2004/08/05 15:40
-	29	((gallium adj nitride) with laser) and solder\$3	USPAT	2004/08/05 15:47
-	143	solder with (stud adj bump)	USPAT	2004/08/05 15:48
-	14	solder with (stud adj bump adj method)	USPAT	2004/08/05 15:48
-	5	("5042042" "5987048" "5998232" "6015979" "6274891").PN.	USPAT	2004/08/05 16:07

-	26	((mounting bonded bonding mounted attaching attached soldering soldered) with (laser ld ((light radiation) adj (source emit\$4))) with (substrate sub\$1mount mount)) same solder\$3 same electrode same ((align\$4 positioning) with (optical laser ((light radiation) adj (source emit\$4))))	USPAT	2004/08/05 17:08
-	0	tokukaihei.in.	USPAT;	2004/08/05 17:08
-	1	07235729.pn.	EPO; JPO JPO	2004/08/17 14:18
-	140900	(plural\$3 multiple two several second) with (laser ((light radaition) adj (source emit\$4)))	USPAT	2004/08/17 14:19
-	2359	(plural\$3 multiple two several second) with (laser ((light radaition) adj (source emit\$4))) with (mount\$3 solder\$3 disposed) with (substrate)	USPAT	2004/08/17 14:20
-	706	(plural\$3 multiple two several second) with (laser ((light radaition) adj (source emit\$4))) with (mount\$3 solder\$3 disposed) with (substrate) with semiconductor	USPAT	2004/08/17 14:21
-	156	(plural\$3 multiple two several second) with (laser ((light radaition) adj (source emit\$4))) with (mount\$3 solder\$3 disposed) with (substrate) with semiconductor with electrode	USPAT	2004/08/17 14:29
-	9	((plural\$3 multiple two several second) near3 (laser ((light radaition) adj (source emit\$4)))) with (mount\$3 solder\$3 disposed) with (substrate) with semiconductor) same (electrode near3 (plural\$3 multiple))	USPAT	2004/08/17 14:22
-	15	((plural\$3 multiple two several second) with (laser ((light radaition) adj (source emit\$4))) with (mount\$3 solder\$3 disposed) with (substrate) with semiconductor) same electrode same (solder\$3)	USPAT	2004/08/17 14:25
-	32	((plural\$3 multiple two several second) near2 (laser ((light radaition) adj (source emit\$4)))) with (mount\$3 solder\$3 disposed) with (substrate) with semiconductor with electrode	USPAT	2004/08/17 14:30
-	2	((plural\$3 multiple two several second) near2 (laser ((light radaition) adj (source emit\$4)))) with (mount\$3 solder\$3 disposed) with (substrate) with semiconductor) same electrode same solder\$3	USPAT	2004/08/17 14:30